

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A method of bonding ~~two objects together, one of which has a first object having a polymer surface and the other has~~ together with a second object having an electrically conductive or semiconductive surface, ~~which the method is characterized in that it comprises~~ comprising the steps of:
 - a) ~~[[the]]~~ electrografting ~~[[of]]~~ an organic film onto the conductive or semiconductive surface of the second object; and then
 - b) ~~an operation of~~ bonding the polymer surface of the first object to the conductive or semiconductive surface of the second object thus grafted.
2. (Currently Amended) The method as claimed in claim 1, ~~characterized in that in~~ which the electrografting of the organic film is electroinitiated grafting.
3. (Currently Amended) The method as claimed in claim 2, ~~characterized in that in~~ which the organic film is a polymer film.
4. (Currently Amended) The method as claimed in claim 3, ~~characterized in that in~~ which the polymer film is obtained from compounds selected from the group consisting of monomers ~~and/or~~ and prepolymers that are partly or completely functionalized by vinyl groups.
5. (Currently Amended) The method as claimed in claim 4, ~~characterized in that in~~ which the polymer film is obtained from a vinyl monomer ~~chosen from~~ selected from the group consisting of acrylonitrile, methacrylonitrile, acrylates and methacrylates, acrylamides, ~~[[and]]~~ methacrylamides, cyanoacrylates, acrylic acid, ~~[[and]]~~ methacrylic acid, styrene, vinyl halides, N-vinylpyrrolidone, 2-vinylpyridine, 4-vinylpyridine and vinyl-terminated telechelic compounds.

6. (Currently Amended) The method as claimed in claim 3, ~~characterized in that~~ in which the polymer film is obtained from compounds selected from the group consisting of monomers and/or and prepolymers that are partly or completely functionalized by cyclic groups that can be cleaved by nucleophilic or electrophilic attack.

7. (Currently Amended) The method as claimed in claim 2, ~~characterized in that~~ in which the organic film is obtained from diazonium, sulfonium, phosphonium or iodonium salts, or mixtures thereof.

8. (Currently Amended) The method as claimed in claim 1, ~~characterized in that~~ in which the bonding ~~operation~~ consists of hotmelt bonding or cold bonding or a combination of the two thereof.

9. (Currently Amended) The method as claimed in claim 8, ~~characterized in that~~ in which the cold bonding is carried out by means of a substance capable of dissolving or swelling the polymer surface to be bonded and the organic film electrografted onto the conductive or semiconductive surface.

10. (Currently Amended) The method as claimed in claim 1, ~~characterized in that~~ in which the polymer constituting the polymer surface is ~~chosen from~~ selected from the group consisting of polyethylenes, polypropylenes, polystyrenes, polyacrylonitriles, polysiloxanes, polyesters, polyorthoesters, polycaprolactones, polybutyrolactones, polyacrylics, polymethacrylics, polyacrylamides, epoxide resins, copolymers thereof and blends thereof.

11. (Currently Amended) The method as claimed in claim 1, ~~characterized in that~~ in which the polymer constituting the polymer surface is a hotmelt polymer.

12. (Currently Amended) The method as claimed in claim 1, ~~characterized in that~~ in which the polymer surface is a polymer film coating a conductive or semiconductive material.

13. (Withdrawn) A method of manufacturing or renovating composites intended for the aerospace, aeronautical, automotive, biomedical, microelectronics and microsystems industries ,which comprises a step consisting in bonding two objects together by the method of claim 1.

14. (Withdrawn) A method of manufacturing implantable surgical and medical instruments ,which comprises a step consisting in bonding two objects together by the method of claim 1.

15. (Withdrawn) A method of assembling sensitive components of microsystems which comprises a step consisting in bonding two objects together by the method of claim 1.

16. (Withdrawan) A structure comprising two objects, one of which has an electrically conductive or semiconductive surface and the other has a polymer surface, these surfaces being bonded to each other via an organic film with a thickness of less than 1 μm .

17. (Withdrawn) A method of packaging of Microsystems, which comprises a step consisting in bonding two objects together by the method of claim 1.